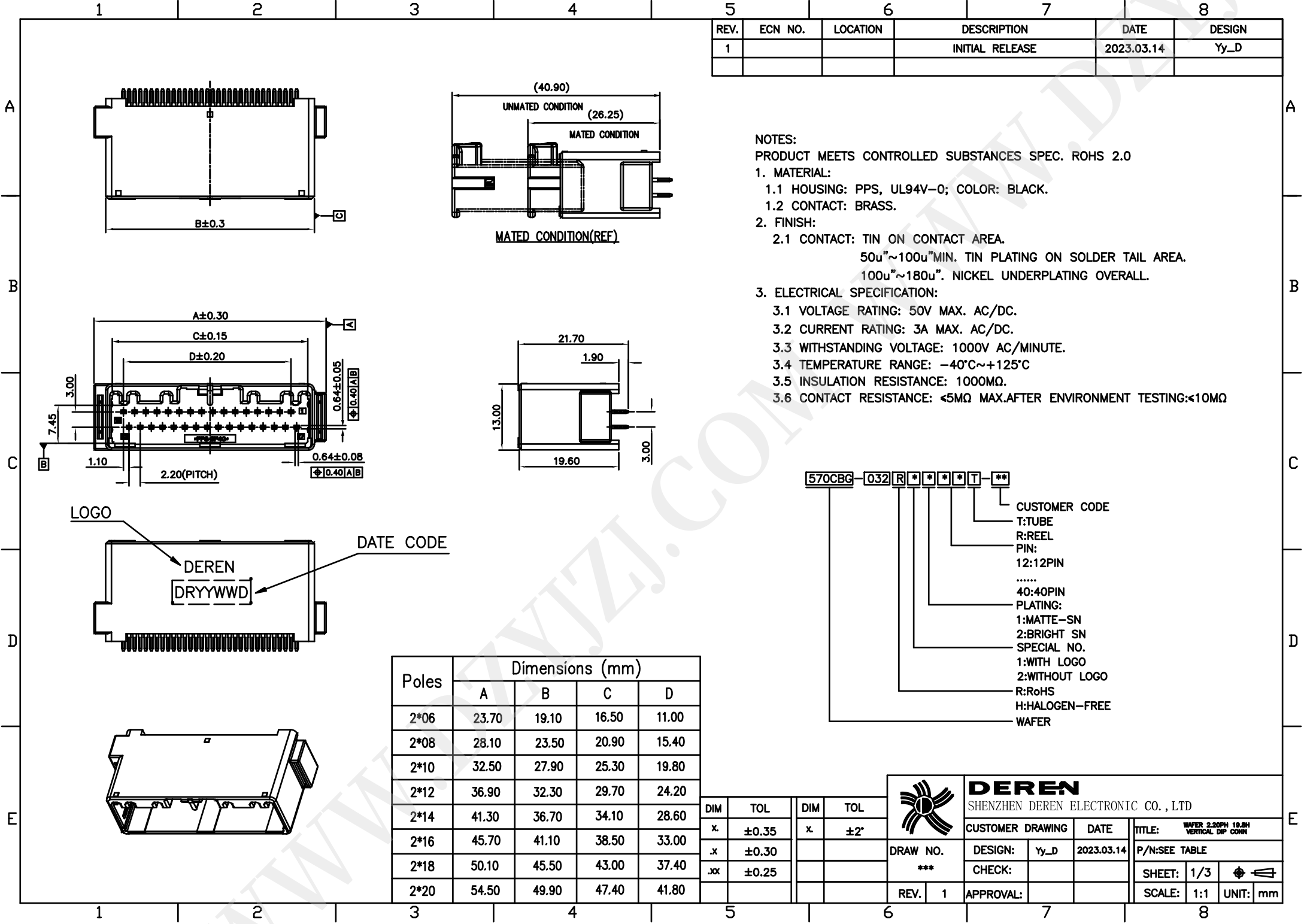




REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
1			INITIAL RELEASE	2023.03.14	Yy_D

- NOTES:
PRODUCT MEETS CONTROLLED SUBSTANCES SPEC. ROHS 2.0
1. MATERIAL:
1.1 HOUSING: PPS, UL94V-0; COLOR: BLACK.
1.2 CONTACT: BRASS.
2. FINISH:
2.1 CONTACT: TIN ON CONTACT AREA.
50u"~100u"MIN. TIN PLATING ON SOLDER TAIL AREA.
100u"~180u". NICKEL UNDERPLATING OVERALL.
3. ELECTRICAL SPECIFICATION:
3.1 VOLTAGE RATING: 50V MAX. AC/DC.
3.2 CURRENT RATING: 3A MAX. AC/DC.
3.3 WITHSTANDING VOLTAGE: 1000V AC/MINUTE.
3.4 TEMPERATURE RANGE: -40°C~+125°C
3.5 INSULATION RESISTANCE: 1000MQ.
3.6 CONTACT RESISTANCE: <5MQ MAX.AFTER ENVIRONMENT TESTING:<10MQ

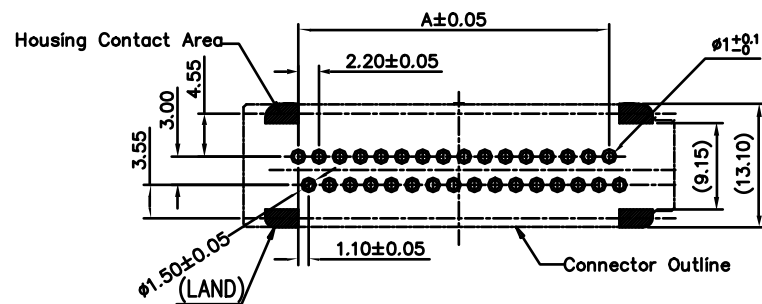
570CBG-032R****T-**-**

CUSTOMER CODE
T:TUBE
R:REEL
PIN:
12:12PIN
.....
40:40PIN
PLATING:
1:MATTE-SN
2:BRIGHT SN
SPECIAL NO.
1:WITH LOGO
2:WITHOUT LOGO
R:RoHS
H:HALOGEN-FREE
WAFER

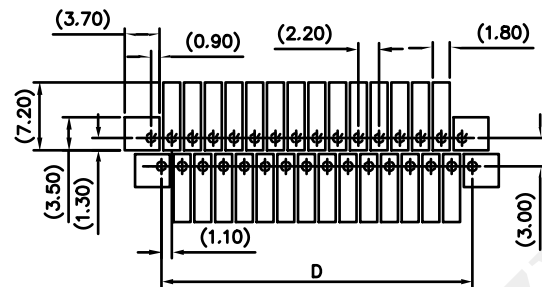
Poles	Dimensions (mm)			
	A	B	C	D
2*06	23.70	19.10	16.50	11.00
2*08	28.10	23.50	20.90	15.40
2*10	32.50	27.90	25.30	19.80
2*12	36.90	32.30	29.70	24.20
2*14	41.30	36.70	34.10	28.60
2*16	45.70	41.10	38.50	33.00
2*18	50.10	45.50	43.00	37.40
2*20	54.50	49.90	47.40	41.80

DIM	TOL	DIM	TOL
x	±0.35	x	±2°
.x	±0.30		
.xx	±0.25		

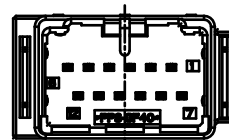
		DEREN					
		SHENZHEN DEREN ELECTRONIC CO., LTD					
DRAW NO. ***		CUSTOMER DRAWING		DATE		TITLE: WAFER 2.20PH 19.8H VERTICAL DIP CONN	
		DESIGN: Yy_D		2023.03.14		P/N:SEE TABLE	
		CHECK:				SHEET: 1/3 	
REV.	1	APPROVAL:				SCALE: 1:1	UNIT: mm



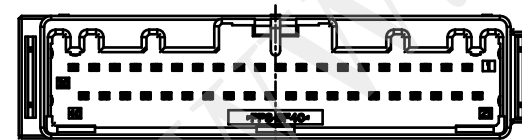
APPLICABLE P.C.B LAYOUT(REF.)
P.C.B THICKNESS $t=1.6\text{mm}$



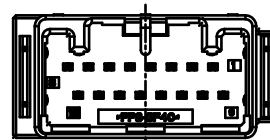
METAL MASK DIMENSIONS(REF.)
MASK THICKNESS $T=0.15\text{mm}$



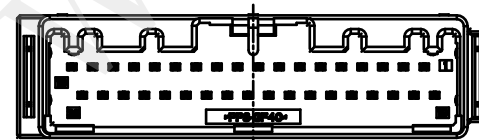
2*06PIN



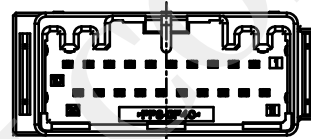
2*20PIN



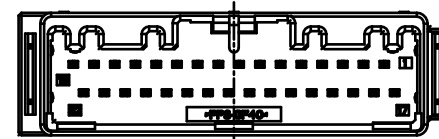
2*08PIN



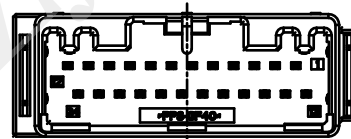
2*18PIN



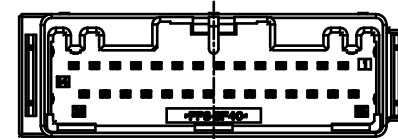
2*10PIN



2*16PIN



2*12PIN

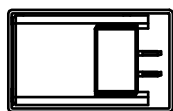
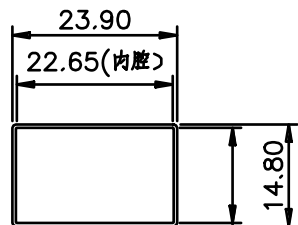


2*14PIN

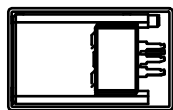
DIM	TOL	DIM	TOL
x	± 0.35	x	$\pm 2^\circ$
.x	± 0.30		
.xx	± 0.25		



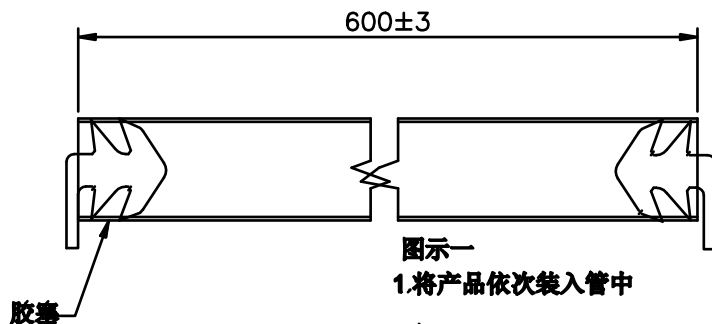
DEREN SHENZHEN DEREN ELECTRONIC CO., LTD			
CUSTOMER DRAWING		DATE	TITLE: WAFER 2.20PH 19.0H VERTICAL DIP CONN
DESIGN:	yy_D	2023.03.14	P/N:SEE TABLE
CHECK:			SHEET: 2/3
APPROVAL:			SCALE: 1:1 UNIT: mm



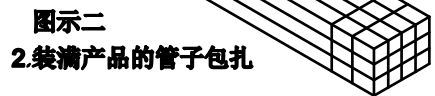
匹配图不带鱼叉



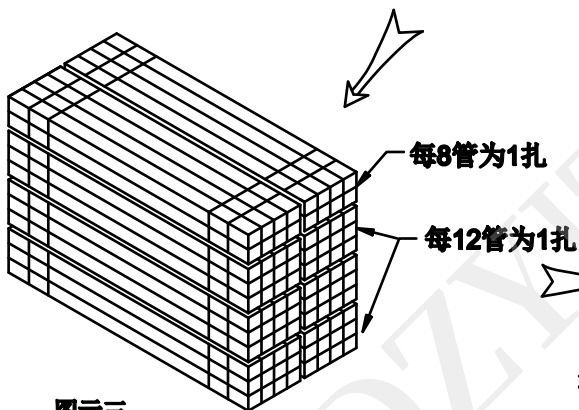
匹配图带鱼叉



图示一
1.将产品依次装入管中

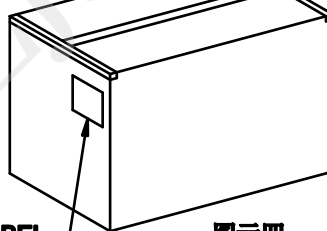


图示二
2.装满产品的管子包扎



图示三
3.将每扎管子包扎

胶带ADHESIVE
TAPE



图示四
4.装箱, 封胶

说明:

- 1.将产品依图示方向放入真空管内, 方向须一致, 每个真空管放的产品数量依Pin数不同而不同, 具体详见包装明细表, 真空管两头用胶塞塞住, 如图示一。
- 2.将装好产品的真空管平放在桌面上以4PCS为一排然后再叠放3列或2列为1把如图二或图三, 整理好后用PE膜将1把真空管两头PE膜缠绕包好, 并在左边PE膜处贴1PCS产品标签, 如图示二。
- 3.将上步完成的产品以每把进行包扎, 包装成一整扎, 以图示三
- 4.将包扎好产品放入纸箱内, 并将纸箱用胶带封好, 在其侧面右上角贴上出货标签。
- 5.纸箱规格: 600*200*180mm 真空管规格: 600*14.4*14.6mm
- 6.纸箱厚度: 6~7mm

PIN数	每支真空产品 数量PCS/管	每箱真空管数量 PCS管/箱	每箱包装数量 PCS/箱
2*06	24	88	2112
2*08	20	88	1760
2*10	17	88	1496
2*12	15	88	1320
2*14	13	88	1144
2*16	12	88	1056
2*18	11	88	968
2*20	10	88	880

DIM	TOL	DIM	TOL
x		x	
.x			
.xx			



DEREN

SHENZHEN DEREN ELECTRONIC CO., LTD

CUSTOMER DRAWING		DATE		TITLE: WAFER 2.20PH 19.8H VERTICAL DIP CONN	
DESIGN: Yy_D		2023.03.14		P/N: SEE TABLE	
CHECK:				SHEET: 3/3	
APPROVAL:				SCALE: N/A UNIT: mm	